

## **ABSTRACT OF THE DISCLOSURE**

The present invention is related to a method for securing a polishing pad to the platen for use in chemical-mechanical polishing. Specifically, a polishing pad is attached to a platen using a reclosable, hook-and-pile fastener, whereby the platen-attachment fastener may be reused. Separate embodiments are disclosed for attaching porous and nonporous polishing pads.

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